- Operation from Very Slow Edges
- Improved Line-Receiving Characteristics
- High Noise Immunity

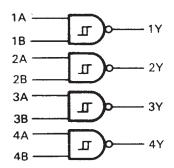
description

Each circuit functions as a 2-input NAND gate, but because of the Schmitt action, it has different input threshold levels for positive (V_{T+}) and for negative going (V_{T-}) signals.

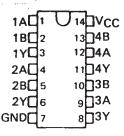
These circuits are temperature-compensated and can be triggered from the slowest of input ramps and still give clear, jitter-free output signals.

The SN54132, SN54LS132, and SN54S132 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74132, SN74LS132, and SN74S132 are characterized for operation from 0°C to 70°C.

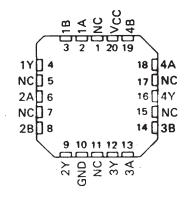
logic diagram (positive logic)



SN54132, SN54LS132, SN54S132 . . . J OR W PACKAGE SN74132 . . . N PACKAGE SN74LS132, SN74S132 . . . D OR N PACKAGE (TOP VIEW)

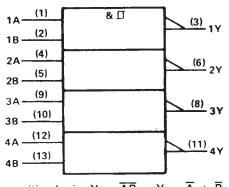


SN54LS132, SN54S132 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

logic symbol†



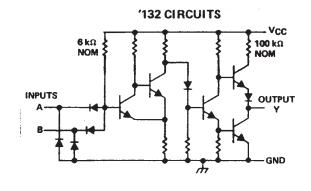
positive logic: $Y = \overline{AB}$ or $Y = \overline{A} + \overline{B}$

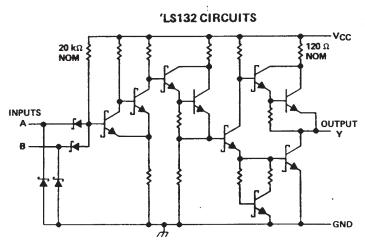
[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

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schematics





'S132 CIRCUITS -vcc 2.8 kΩ NOM **50** Ω NOM **INPUTS** OUTPUT GND

Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| Supply voltage, VCC (see Note 1) | 7 V |
|---------------------------------------|-------------------------|
| Input voltage: '132, 'S132 | 5.5 V |
| 'LS132 | |
| Operating free-air temperature: SN54' | – 55° C to 125°C |
| SN74' | 0°C to 70°C |
| Storage temperature range | - 65°C to 150°C |

NOTE 1: Voltages values are with respect to network ground terminal.



recommended operating conditions

| | | | SN5413 | 2 | | UNIT | | |
|-----|--------------------------------|------|--------|-------|------|------|-------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | UNIT |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | ٧ |
| Іон | High-level output current | | | - 0.8 | | | - 0.8 | mA |
| IOL | Low-level output current | | | 16 | | | 16 | mA |
| TA | Operating free-air temperature | - 55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDIT | rions† | MIN | TYP‡ | MAX | UNIT |
|---|------------------------|--------------------------|----------------------------|------|--------|-------|------|
| V _{T+} | V _{CC} = 5 V | | | 1.5 | 1.7 | 2 | V |
| v _{T-} | V _{CC} = 5 V | | | 0.6 | 0.9 | 1.1 | V |
| V _{hys} (V _{T+} -V _{T-}) | V _{CC} = 5 V | | | 0.4 | 0.8 | | V |
| ViK | V _{CC} = MIN, | I _I = - 12 mA | | | | - 1.5 | V |
| VOH | V _{CC} = MIN, | V ₁ = 0.6 V, | t _{OH} = - 0.8 mA | 2.4 | 3.4 | | V |
| VOL | V _{CC} = MIN, | V ₁ = 2 V, | IOL = 16 mA | | 0.2 | 0.4 | V |
| I _{T+} | V _{CC} = 5 V, | V1 = VT+ | | | - 0.43 | | mΑ |
| 1 _T _ | V _{CC} = 5 V, | Λ1 = Λ ^L | | | - 0.56 | | mA |
| l ₁ | V _{CC} = MAX, | V ₁ = 5.5 V | | | | 1 | mA |
| ΊΗ | V _{CC} = MAX, | V ₁ = 2.4 V | | | - | 40 | μА |
| li L | V _{CC} = MAX, | V _{1L} = 0.4 V | | | - 0.8 | - 1.2 | mA |
| los§ | V _{CC} = MAX | | | - 18 | • | - 55 | mA |
| ГССН | V _{CC} = MAX | | | | 15 | 24 | mA |
| ICCL | V _{CC} = MAX | | | | 26 | 40 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CON | TEST CONDITIONS | | | |
|------------------|-----------------|----------------|--------------------|------------------------|----|----|----|
| tPLH. | Δον | ~ | $R_1 = 400 \Omega$ | C ₁ = 15 pF | 15 | 22 | ns |
| ^t PHL | Any | • | 11 400 32, | οΓ - 12 bι | 15 | 22 | ns |

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time.

SN54LS132, SN74LS132 QUADRUPLE 2-INPUT POSITIVE-NAND SCHMITT TRIGGERS

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recommended operating conditions

| | | S | N54LS1 | 32 | S | UNIT | | |
|-----|--------------------------------|-----|--------|-------|------|------|------|------|
| | | MIN | NOM | MAX | MIN | MOM | MAX | UNIT |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| ЮН | High-level output current | | | - 0.4 | | | -0.4 | mA |
| IOL | Low-level output current | | *** | 4 | | | 8 | mA |
| TA | Operating free-air temperature | 55 | | 125 | 0 | | 70 | °c |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDI | riouet | S | N54LS1 | 32 | SI | N74LS1 | 32 | UNIT |
|---|------------------------|----------------------------------|---------------------------------------|------|--------|-------|------|--------|--------------|------|
| PARAMETER | | 1EST CONDI | TIONS | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | UNIT |
| V _{T+} | V _{CC} = 5 V | | | 1.4 | 1.6 | 1.9 | 1.4 | 1.6 | 1.9 | V |
| ∨ _{T−} | V _{CC} = 5 V | | | 0.5 | 8.0 | 1 | 0.5 | 8.0 | 1 | V |
| V _{hγs} (V _{T +} -V _{T -}) | V _{CC} = 5 V | | | 0.4 | 0.8 | | 0.4 | 0.8 | | V |
| VIK | V _{CC} = MIN, | I _I = - 18 mA | | | | - 1.5 | | | - 1.5 | V |
| Voн | V _{CC} = MIN, | V ₁ = 0.5 V, | IOH = - 0.4 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | ٧ |
| VOL | VCC = MIN, | V _I = 1.9 V | IOL = 4 mA | | 0.25 | 0.4 | I | 0.25 | 0.4 | V |
| VOL | A C.C 101114' | V1 - 1.5 V | IOL = 8 mA | | | | | 0.35 | 0.5 |] |
| 1 _{T+} | V _{CC} = 5 V, | V _I = V _{T+} | | _ | - 0.14 | | - | - 0.14 | | mA |
| IT- | V _{CC} = 5 V, | V1 = VT_ | | - | - 0.18 | | - | - 0.18 | | mA |
| l _l | V _{CC} = MAX, | V _I = 7 V | | | | 0.1 | | | 0.1 | mA |
| ЧН | V _{CC} = MAX, | V ₁ = 2.7 V | | | | 20 | | | 20 | μА |
| 11L | V _{CC} = MAX, | V _{IL} = 0.4 V | | | | - 0.4 | | | - 0.4 | mA |
| os § | V _{CC} = MAX | , | · · · · · · · · · · · · · · · · · · · | - 20 | | - 100 | - 20 | | - 100 | mA |
| Iссн | V _{CC} = MAX | | | | 5.9 | 11 | | 5.9 | 11 | mA |
| ¹ CCL | V _{CC} = MAX | | | | 8.2 | 14 | | 8.2 | 14 | mA |

 $^{^{\}dagger}$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see figure 1)

| | PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CON | IDITIONS | MIN | TYP | MAX | UNIT |
|---|------------------|-----------------|----------------|-------------------|------------------------|-----|-----|-----|------|
| | ^t PLH | Any | , | $R_1 = 2 k\Omega$ | C ₁ = 15 pF | | 15 | 22 | ns |
| - | ^t PHL | , ,,,, | ' | 11 2 1100, | OL = 13 D1 | | 15 | 22 | ns |

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second

SN54S132, SN74S132 QUADRUPLE 2-INPUT POSITIVE-NAND SCHMITT TRIGGERS

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recommended operating conditions

| | | | SN54S1 | 32 | | UNIT | | |
|-----|--------------------------------|------|--------|------------|------|------|------------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | UNII |
| Vcc | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| Іон | High-level output current | | | – 1 | | | – 1 | mA |
| IOL | Low-level output current | | | 20 | | | 20 | mA |
| TA | Operating free-air temperature | - 55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDIT | uovet | | SN54S1 | 32 | : | SN74S1 | 32 | UNIT |
|--|------------------------|--------------------------|--------------|-------------|--------|-------|------|--------------|--------------|------|
| PARAMETER | | TEST CONDIT | ION2. | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | ONT |
| V _{T+} | V _{CC} = 5 V | | | 1.6 | 1.77 | 1.9 | 1.6 | 1.77 | 1.9 | ٧ |
| V _T _ | V _{CC} = 5 V | | | 1.1 | 1.22 | 1.4 | 1.1 | 1.22 | 1.4 | ٧ |
| V _{hys} (V _{T +} -V _{T -}) | V _{CC} = 5 V | | | 0.2 | 0.55 | | 0.2 | 0.55 | | ٧ |
| VIK | V _{CC} = MIN, | I ₁ = - 18 mA | | | | - 1.2 | | | - 1.2 | V |
| Voн | V _{CC} = MIN, | V ₁ = 1.1 V, | IOH = - 1 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | ٧ |
| VOL | V _{CC} = MIN, | $V_1 = 1.9 V$, | IOL = 20 mA | | | 0.5 | | | 0.5 | V |
| I _{T+} | V _{CC} = 5 V, | V1 = VT+ | | | - 0.9 | | | - 0.9 | | mA |
| 1T_ | V _{CC} = 5 V, | VI = VT_ | | | - 1.1 | | | - 1.1 | | mA |
| lį | V _{CC} = MAX, | V _I = 5.5 V | | | | 1 | | | 1 | mA |
| ЧН | V _{CC} = MAX, | V ₁ = 2.7 V | | | | 50 | | | 50 | μA |
| 115 | V _{CC} = MAX, | V _{1L} = 0.5 V | | | | - 2 | | | - 2 | mΑ |
| los§ | V _{CC} = MAX | | | - 40 | | - 100 | - 40 | | – 100 | mΑ |
| ССН | V _{CC} = MAX | | | | 28 | 44 | | 28 | 44 | mA |
| ICCL | V _{CC} = MAX | | | | 44 | 68 | | 44 | 68 | mA |

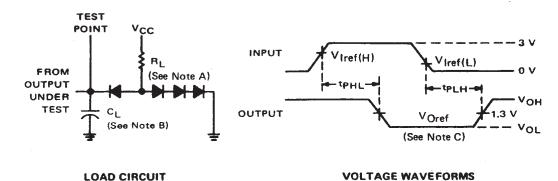
 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CON | DITIONS | MIN | TYP | MAX | UNIT |
|------------------|-----------------|----------------|----------------------|------------------------|-----|-----|------|------|
| t _{PLH} | A or B | V | $R_1 = 280 \Omega_s$ | C ₁ = 15 pF | | 7 | 10.5 | ns |
| tPHL | 70,0 | ' | 11 - 200 14, | O[- 13 br | | 8.5 | 13 | nis |

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. All diodes are 1N3064 or equivalent.

B. C_L includes probe and jig capacitance.

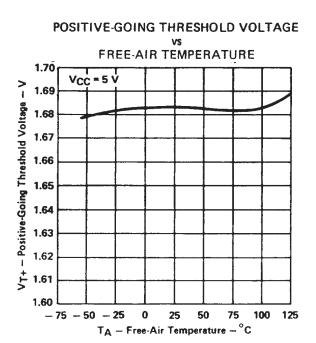
C. Generator characteristics and reference voltages are:

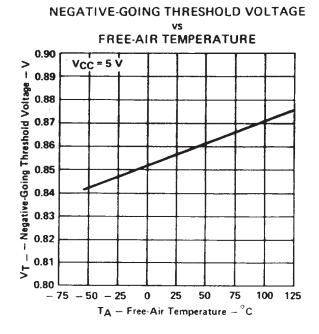
| | G | enerator C | haracteris | tics | Reference Voltages | | | | | |
|-----------------|------|------------|------------|--------|--------------------|-----------|--------|--|--|--|
| | Zout | PRR | tr | tf | VI ref(H) | VI ref(L) | VO ref | | | |
| SN54'/SN74' | 50 | 1 MHz | 10 ns | 10 ns | 1.7 V | 0.9 V | 1.5 V | | | |
| SN54LS'/SN74LS' | 50 | 1 MHz | 15 ns | 6 ns | 1.6 V | 0.8 V | 1.3 V | | | |
| 'S132 | 50 | 1 MHz | 2.5 ns | 2.5 ns | 1.8 V | 1.2 V | 1.5 V | | | |

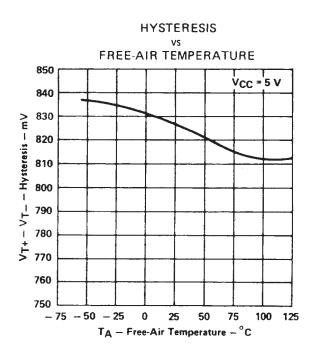
FIGURE 1

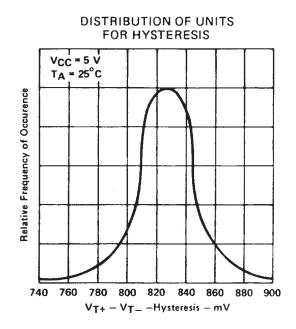


TYPICAL CHARACTERISTICS OF '132 CIRCUITS

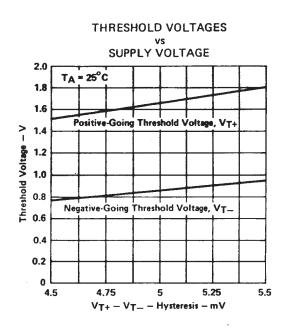


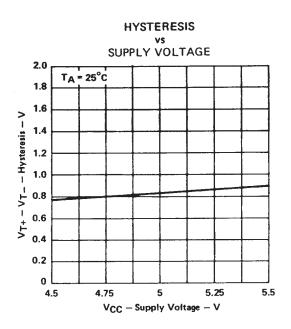


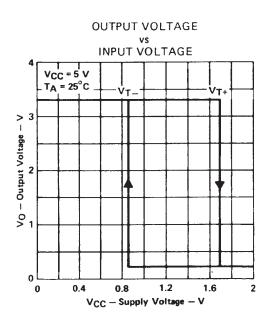




TYPICAL CHARACTERISTICS OF '132 CIRCUITS





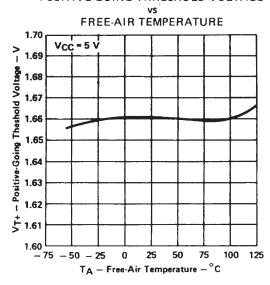


 $^{^{\}dagger}$ Data for temperatures below 0° C and 70° C and supply below 4.75 V and above 5.25 V are applicable for SN54132 only.

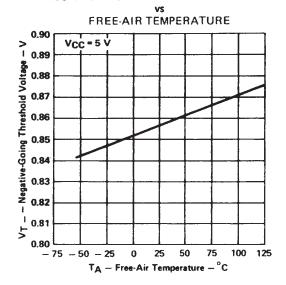


TYPICAL CHARACTERISTICS OF 'LS132 CIRCUITS

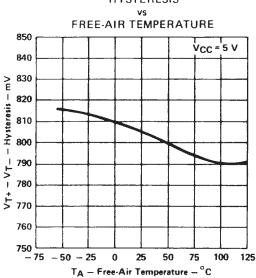
POSITIVE-GOING THRESHOLD VOLTAGE



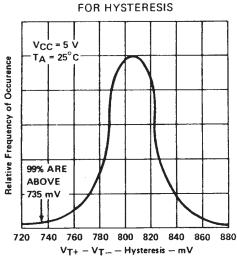
NEGATIVE-GOING THRESHOLD VOLTAGE



HYSTERESIS



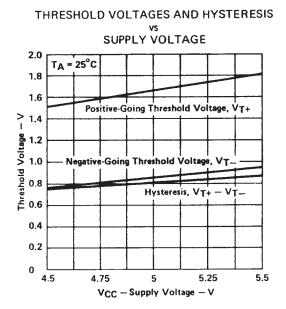
DISTRIBUTION OF UNITS

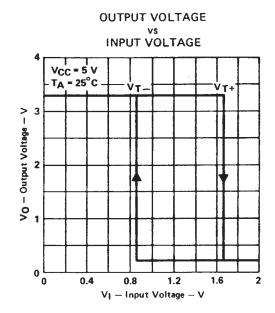


Data for temperatures below 0°C and above 70°C and supply voltages below 4.75 V and above 5.25 V are applicable for SN54LS132 only.



TYPICAL CHARACTERISTICS OF 'LS132 CIRCUITS

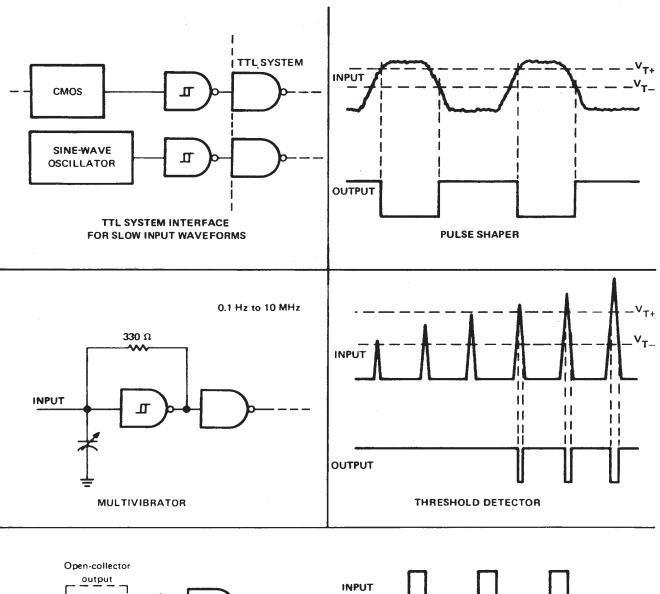


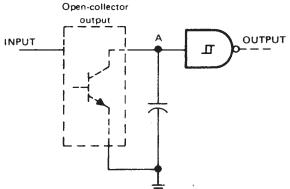


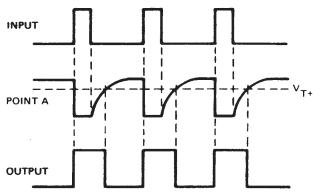
[†] Data for temperatures below 0°C and above 70°C and supply voltages below 4.75 V and above 5.25 V are applicable for SN54LS132 only.



TYPICAL APPLICATION DATA







PULSE STRETCHER





PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|-------------------------|------------------|------------------------------|
| 7600401CA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| 7600401DA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| 7600401DA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/31303BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/31303BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN54132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN54LS132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54LS132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN74132N | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74132N | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS132D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS132N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS132N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |





18-Sep-2008

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|-----------------------------|
| SN74LS132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS132NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS132NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS132NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS132NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S132D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S132D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIN |
| SN74S132N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S132N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S132N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S132NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S132NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |





ti.com 18-Sep-2008

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | n MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|-------------------------|------------------|--------------------------------|
| SNJ54132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SNJ54132J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SNJ54LS132FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS132FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS132W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54LS132W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S132FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S132FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54S132J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54S132W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S132W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

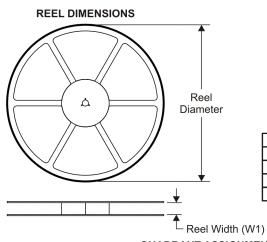
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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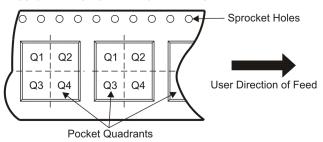
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

| | Dimension designed to accommodate the component width |
|----|---|
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

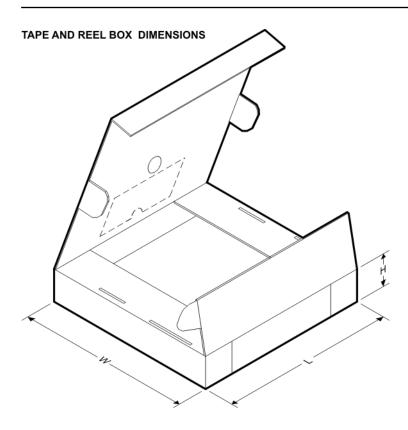
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|-----------------|--------------------|----|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| SN74LS132DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LS132NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74S132DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

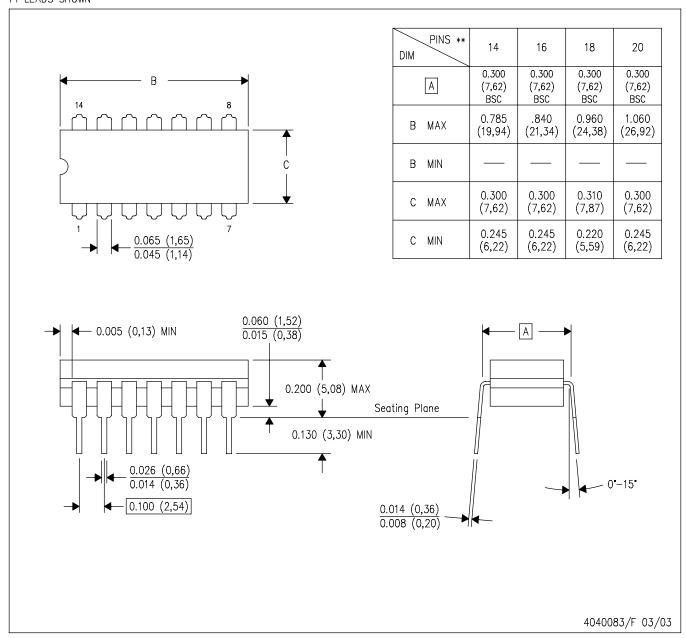




*All dimensions are nominal

| 7 til dilitioriolorio dio monimal | | | | | | | |
|-----------------------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
| SN74LS132DR | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |
| SN74LS132NSR | SO | NS | 14 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74S132DR | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |

14 LEADS SHOWN

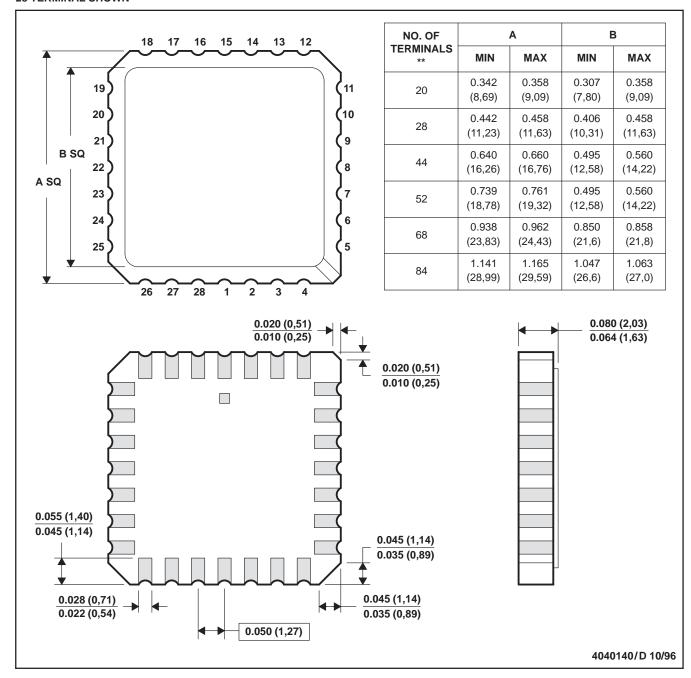


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

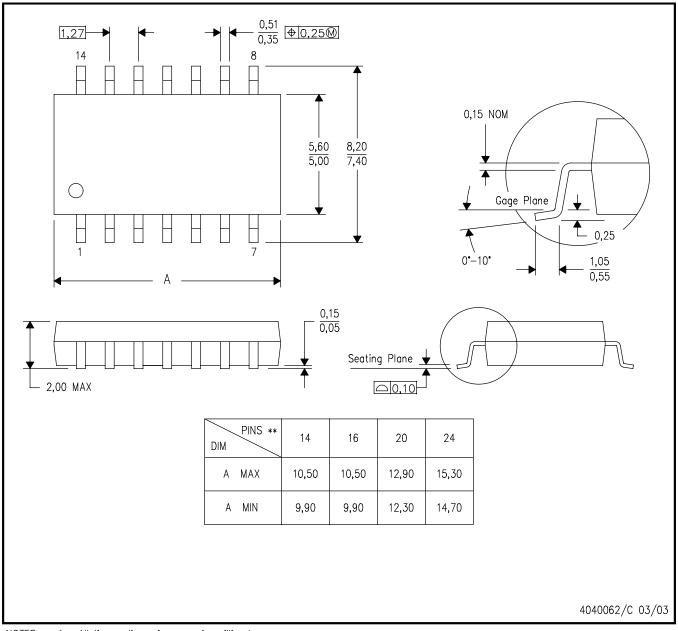


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

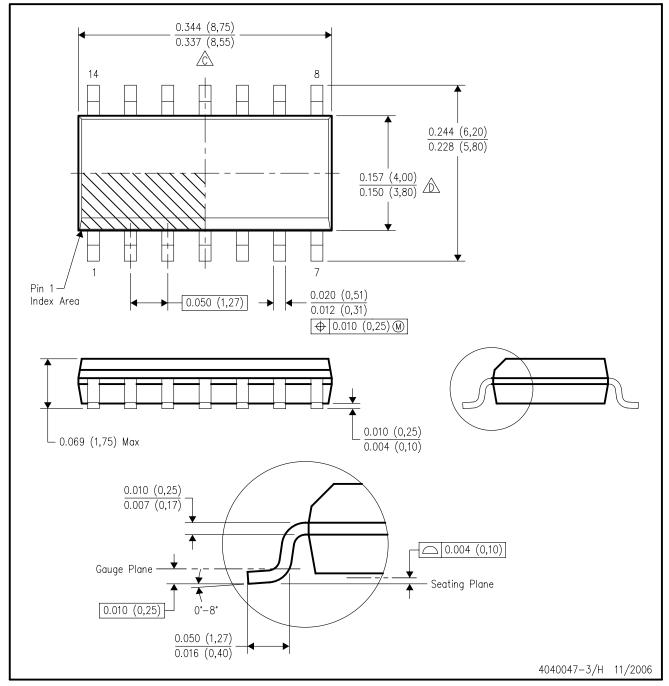


- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

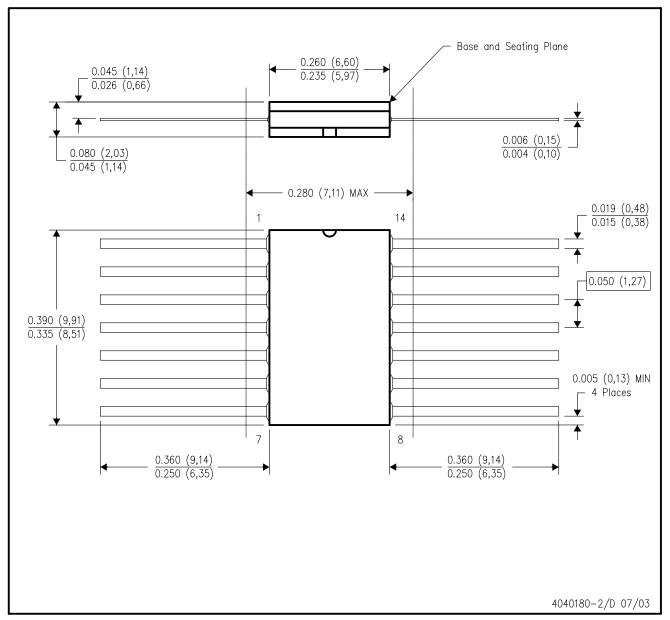


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



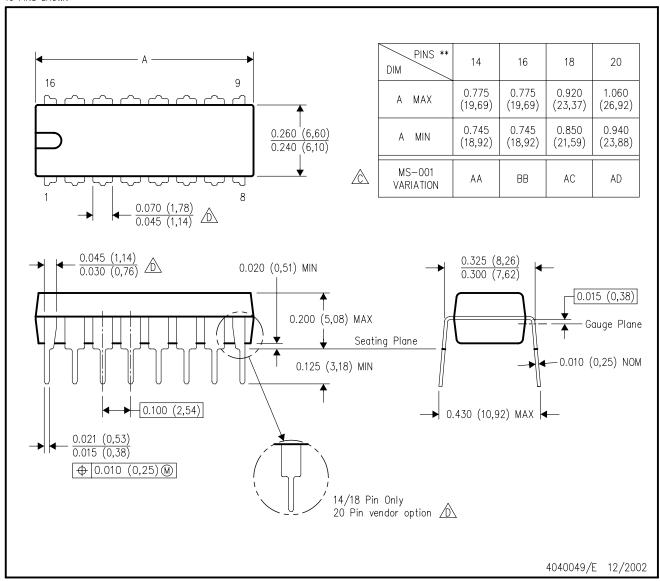
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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